

Legal Statement

Materials Declaration Form

IPC	1752	Manajan	2					
Form Type *	Distribute	version	2					
Sectionals *	Material Info	Subsectionals *	A-D					
	Manufacturing Info		* : Required Field					
Supplier Information								
Company Name *	STMicroelectronics	Response Date *	2019-01-15					
Company Unique ID	NL 008751171B01							
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section					
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section					
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion					
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section					
Supplier Comment Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support.html								
Uncertainty Statement								
While STMicroelectronics has end STMicroelectronics disclaims all w merchantability, fitness for a part directly or indirectly, from the use	eavored to provide information which i arranties, express or implied related to icular purpose and non-infringement. S' or inability to use this document and/or	s accurate and up to date, this do this document and its contents, in T shall have no responsibility and its contents.	cument and its contents are provided on a strict 'as is' and 'as available' ba cluding but not limited to implied warranties of completeness, truth, accura assumes no liability for any cost, loss or damage of any kind which could ar					
Logal Statement								
			u e Chandand					
Supplier Acceptance *	true	Legal Decla	ration * Standard					
	Supplier certifies that it gathered the date that Supplier completes t	the provided information and s his form. Supplier acknowledges t	uch information is true and correct to the best of its knowledge and belief, as that Company will rely on this certification in determining the compliance of					

may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product									
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date					
SMC30J6.5CA	8HZH*TWBV75M	А	64BA	2019-01-15					
	Amount	UoM	ST ECOPACK Grade						
	250.00	mg	ECOPACK2						
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)							

Manufacturing information						
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles				
1	260	3				
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	life guamented		
NA	Tin (Sn), matte	Copper Alloy		metadghiomod		
Package Designator	Size	Nbr of instances	Shape			
SOL	6 69-5 63-7 38	2	Lbend			

Comment SMC CLIP (SOD 15)

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015							
	Response						
1 - Product(s) meets EU RoHS requirement	FALSE						
2 - Product(s) meets EU RoHS requirement apply)	FALSE						
3 - Product(s) meets EU RoHS requirement	TRUE						
4 - Product(s) does not meet EU RoHS req	FALSE						
Exemption Id.	Exemption Id. Description						
7a Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)							

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017						
Query Response						
1 - Product(s) meets EU ELV requirements without any exemptions FALSE						
2 - Product(s) meets EU RoHS requiremen	TRUE					
Exemption Id.	cription					
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)					

QueryList : California Prop65 list, dated 25th May 2018								
Qu	Response							
1 - The product does not contain identified substance from California Prop 65 List, no	FALSE							
2 - The product is containing below substance(s) from California Prop 65 List, no expo	TRUE							
Substance	ppm in product							
Nickel	0.87	Die - Leadframe	3460					
Lead	27832							

QueryList : REACH-27th June 2018								
	Response							
1 - Product(s) does not contain REACH Sul	FALSE							
CategoryLevel_Name	tegoryLevel_Name CategoryLevel_Threshold amount in product (mg) Application							
Lead	ad 1000 ppm 6.96 Soft solder							
2 - Product(s) does not contain REACH definition within REACH	FALSE							
CategoryLevel_Name CategoryLevel_Threshold Amount in Embedded Article / Application - Article / Homogene Homogeneous Material (mg) Material				ppm in Article /Homogeneous Material				
Lead	1000 ppm 6.96 Soft solder							

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document				Mfr Item Name	8HZH*TWBV75M							
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	9.345	mg	supplier	die	Silicon (Si)	7440-21-3		9.059	mg	969395	36236
				supplier	metallization	Aluminium (Al)	7429-90-5		0.053	mg	5671	212
				supplier	metallization	Gold (Au)	7440-57-5		0.038	mg	4066	152
				supplier	metallization	Nickel (Ni)	7440-02-0		0.038	mg	4066	152
				supplier	Passivation	Silicon Oxide	7631-86-9		0.052	mg	5564	208
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.035	mg	3745	140
				supplier	back side metallization	Gold (Au)	7440-57-5		0.012	mg	1286	48
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.058	mg	6207	232
Leadframe	M-004 Copper and its alloys	79.540	mg	supplier	alloy	Copper (Cu)	7440-50-8		78.668	mg	989037	314672
				supplier	alloy	Iron (Fe)	7439-89-6		0.079	mg	993	316
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.024	mg	302	96
				supplier	metallization	Nickel (Ni)	7440-02-0		0.769	mg	9668	3076
Soft solder	Solder	7.561	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	6.958	mg	920249	27832
				supplier	solder	Silver (Ag)	7440-22-4		0.188	mg	24864	752
				supplier	solder	Tin (Sn)	7440-31-5		0.377	mg	49861	1508
				supplier	solder	flux residue	Proprietary		0.038	mg	5026	152
Encapsulation	M-011 Other inorganic materials	112.068	mg	supplier	mold compound	Amorphous Silica	7631-86-9		81.921	mg	730994	327684
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		21.293	mg	190001	85172
				supplier	mold compound	Phenol resin	9003-35-4		3.362	mg	30000	13448
				supplier	mold compound	Bisphenol A-bisphenol A diglycidyle ether poly	25036-25-3		3.362	mg	30000	13448
				supplier	mold compound	Carbon black	1333-86-4		1.009	mg	9003	4036
				supplier	mold compound	Triphenylphophine	603-35-0		0.785	mg	7005	3140
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		0.336	mg	2997	1344
Connections coating	Solder	1.972	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.972	mg	1000000	7888
Clip	M-004 Copper and its alloys	39.514	mg	supplier	alloy	Copper (Cu)	7440-50-8		39.514	mg	1000000	158056